

**IN THE CLAIMS:**

Please note that, pursuant to 37 CFR 1.121(c)(3) all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity and for the convenience of the Patent Office.

Please amend claims 3 and 4 as set forth below.

1. A method of forming an integrated circuit package, the method comprising:  
forming a lead frame having a plurality of conductors and at least one alignment feature electrically isolated from the plurality of conductors;  
coupling at least some of the plurality of conductors to a semiconductor die; and  
encapsulating the semiconductor die and a portion of the lead frame with an insulating material.

2. The method of claim 1, further comprising removing the at least one alignment feature.

B1  
3. (Amended) A method of forming an integrated circuit package, the method comprising:  
providing a plurality of conductors and at least one alignment feature;  
coupling at least some of the plurality of conductors to a semiconductor die; and  
encompassing the semiconductor die, a portion of each of the plurality of conductors, and  
substantially encompassing the at least one alignment feature with an insulating material.

B2  
4. (Twice Amended) A method of forming and testing an integrated circuit package, the method comprising:  
providing a plurality of conductors and at least one alignment feature;  
electrically coupling at least some of the plurality of conductors to a semiconductor die;  
encompassing the semiconductor die, a portion of each of the plurality of conductors, and  
substantially encompassing the at least one alignment feature with an insulating material;  
coupling the at least one alignment feature encompassed by the insulating material with a portion  
of a testing device; and  
testing the integrated circuit package through at least some of the electrically coupled  
conductors.